



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-01-25
Contact Name *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Authorized Representative *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		


Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPSC10H12DY	BSDK*HC15AT7	A	3068	2018-01-25
	Amount	UoM	Unit type	ST ECOPACK Grade
	1870	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-16.25-4.5	2	Through-hole	
Comment	DO 220			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.15	Die / Leadframe	81
Lead	3.67	Soft solder	1964

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	BSDK*HC15A7					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	3.760	mg	supplier	die	Silicium carbide	409-21-2		3.560	mg	946809	1904
				supplier	metallization	Aluminium (Al)	7429-90-5		0.040	mg	10638	21
				supplier	metallization	Gold (Au)	7440-57-5		0.006	mg	1595	3
				supplier	metallization	Nickel (Ni)	7440-02-0		0.032	mg	8511	17
				supplier	metallization	Silver (Ag)	7440-22-4		0.068	mg	18085	36
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	532	1
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	532	1
				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1596	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.027	mg	7181	16
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.017	mg	4521	9
Leadframe	M-004 Copper and its alloys	1184.409	mg	supplier	alloy	Copper (Cu)	7440-50-8		1182.771	mg	998617	632498
				supplier	alloy	Iron (Fe)	7439-89-6		1.184	mg	1000	633
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.355	mg	300	190
				supplier	metallization	Nickel (Ni)	7440-02-0		0.092	mg	77	49
				supplier	metallization	Phosphorus (P)	7723-14-0		0.007	mg	6	4
				supplier	alloy	Lead (Pb)	7439-92-1	7a-Lead in high mel	3.672	mg	955007	1964
Soft solder	Solder	3.845	mg	JIG - R	solder	Lead (Pb)	7439-92-1		0.967	mg	24967	51
				supplier	solder	Silver (Ag)	7440-22-4		0.096	mg	24967	51
				supplier	solder	Tin (Sn)	7440-31-5		0.077	mg	20026	41
Bonding wires	M-011 Other inorganic materials	2.770	mg	supplier	wire	Aluminium (Al)	7429-90-5		2.770	mg	1000000	1481
Encapsulation	M-011 Other inorganic materials	670.975	mg	supplier	mold compound	Silica, vitreous	60676-86-0		583.748	mg	870000	312165
				supplier	mold compound	Epoxy resin	25068-38-6		67.098	mg	100001	35881
				supplier	mold compound	Phenol resin	29690-82-2		16.774	mg	24999	8970
				supplier	mold compound	Carbon Black	1333-86-4		3.355	mg	5000	1794
Connections coating	Solder	4.241	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.241	mg	1000000	2268